

Electronic Patent Application Fee Transmittal

Application Number:	10055499			
Filing Date:	22-Jan-2002			
Title of Invention:	INTEGRATED CHIP PACKAGE STRUCTURE USING ORGANIC SUBSTRATE AND METHOD OF MANUFACTURING THE SAME			
First Named Inventor/Applicant Name:	Jin-Yuan Lee			
Filer:	Winston Hsu			
Attorney Docket Number:	MEGP0012USA			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appl issue fee	1501	1	1440	1440
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
Total in USD (\$)				1740